ASSOCIATION OF ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under b international and Pan-American copyright conventions.		This docum level parts,	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					als and Mfg Information			
upplier l	Information													
Company name*				ompany unique ID			Unique ID Authority				Response Date*			
nsemi											2024-05-10			
Contact Nar	me		Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized	Representative*		Title - Representative			Phone - Representative*			Email - Representative*					
Product-En	v-Stewards		Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
I	Requester Item Number	Mfr Item	Number	Mfr Item Name		Effective D	ate Versi	ion	Manufacturing Site	W	eight*	UOM	Unit Type	
				Secondary side SM for Low Standby P	IPS OFF Mode controller	2024-05-10 PH1		PH1	7	1.91	mg	Each		
Ianufact	turing Proccess Inform	ation												
Т	Terminal Plating / Grid Array Material Termin			rminal Base Alloy J-STD-020 MSL Rating		Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles					
N	Matte Tin (Sn) - annealed	(CU Alloy	1		260		С	30	second	s 3			
omments														
vel 1 - max	ximum time at peak tempera	ture during sol	dering is 10-3	30 seconds										
or more in	formation regarding materia	al composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreem											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg		Epoxy resin	proprietary data		0.24	mg
			Supplier	Silver (Ag)	7440-22-4		1.92	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.24	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.1128	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0715	mg
			Supplier	Iron (Fe)	7439-89-6		0.9741	mg
			Supplier	Copper (Cu)	7440-50-8		36.399	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0527	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond	0.1	mg	Supplier	Palladium (Pd)	7440-05-3		0.0021	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0976	mg